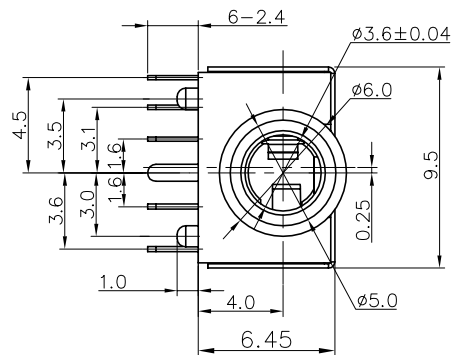
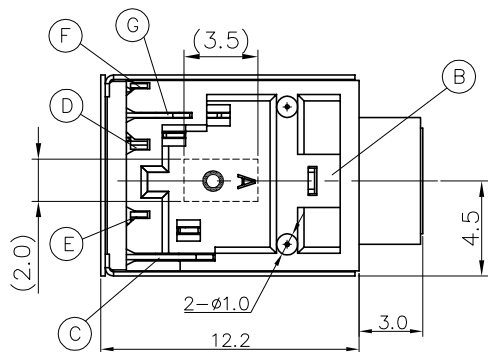
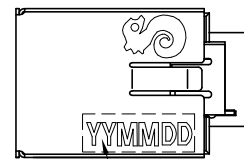
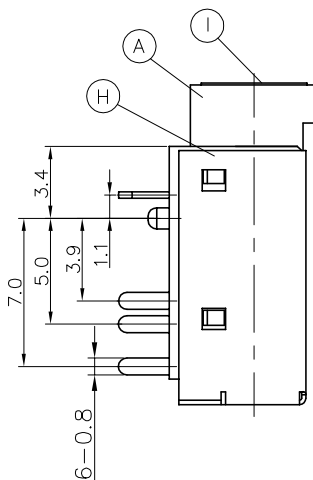
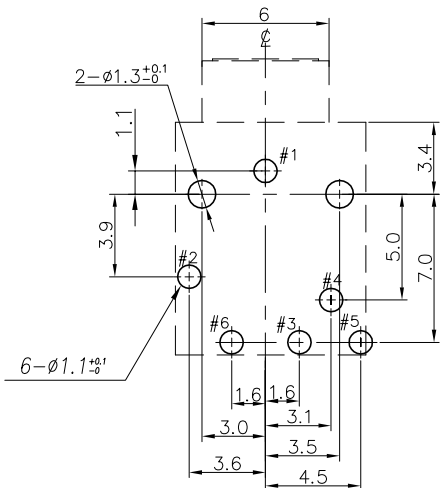


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.:T130820-4A PDR NO.:T130820-4B	MARS	2014.01.17



**SPECIFICATIONS:**

- ELECTRICAL CHARACTERISTICS:
  - RATING: 12V 1A
  - CONTACT RESISTANCE: 30mΩ MAX.(INITIAL)
  - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE
  - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
- MECHANICAL CHARACTERISTICS:
  - INSERTION FORCE :0.4~3.0 KGF
  - WITHDRAWAL FORCE : 0.3~3.0KGF
- LIFE TEST: 5,000 CYCLES MIN.
- OTHER GENERAL SPEC. TO REFER "2.5 3.5 PHONE JACK-SPEC".
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.

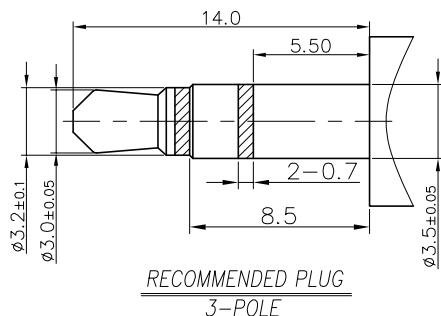
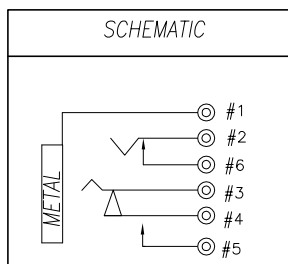


DATE CODE.

"TABLE 1"

P/N:	COLOR
2SJ-B351-S59F	PINK
2SJ-B351-S60F	LIME

RECOMMENDED PCB LAYOUT  
TOP VIEW (TOL.±0.05)



RECOMMENDED PLUG  
3-POLE

I	METAL	1	BRASS	Ni 60u"
H	SHIELDING	1	COPPER ALLOY 0.2T	
G	TRANSFER TERMINAL	1	COPPER ALLOY 0.2T	GOLD FLASH ON CONTACT AREA Sn 120u" ON SOLDER TAIL ALL OVER Ni 60u"
F	BREAK TERMINAL	1	COPPER ALLOY 0.2T	
E	SHUNT TERMINAL-A	1	BRASS 0.2T	GOLD FLASH ON CONTACT AREA ALL OVER 50u" Ni(50%) Min: GOLD FLASH ON CONTACT AREA Sn 120u" ON SOLDER TAIL ALL OVER Ni 50u"
D	RING SPRING	1	COPPER ALLOY 0.2T	
C	TIP SPRING	1	COPPER ALLOY 0.25T	Ag 20u"Min OVER Ni 40~80u"
B	EARTH	1	COPPER ALLOY 0.3T	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	SEE "TABLE 1"
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.  
信音企業股份有限公司

DECIMALS: ANGLES:  
X :±0.5 X :±2°  
X.X :±0.3 X.X :±1°  
X.XX :±0.2

TITLE	3.5Ø PHONE JACK			
DWN	MARS	PART NO. 2SJ-B351-SXXF		
CHKD	BRUCE	SCALE:4:1	UNIT: MM	⊕
APVD	LUSSEN	SIZE: A3	SHEET:1 OF 1	REV: A

CUSTOMER COPY